



# PMV22EN

30 V, 5.2 A N-channel Trench MOSFET

Rev. 1 — 30 March 2011

Product data sheet

## 1. Product profile

### 1.1 General description

N-channel enhancement mode Field-Effect Transistor (FET) in a small SOT23 (TO-236AB) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

### 1.2 Features and benefits

- Logic-level compatible
- Trench MOSFET technology
- Very fast switching

### 1.3 Applications

- Relay driver
- Low-side loadswitch
- High-speed line driver
- Switching circuits

### 1.4 Quick reference data

Table 1. Quick reference data

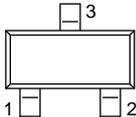
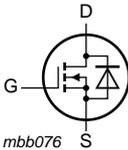
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DS}$	drain-source voltage	$T_{amb} = 25\text{ °C}$	-	-	30	V
$V_{GS}$	gate-source voltage		-20	-	20	V
$I_D$	drain current	$V_{GS} = 10\text{ V}; T_{amb} = 25\text{ °C}$	[1]	-	5.2	A
<b>Static characteristics</b>						
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10\text{ V}; I_D = 5.2\text{ A};$ pulsed; $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.01; T_j = 25\text{ °C}$	-	17	22	m $\Omega$

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm<sup>2</sup>.



## 2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate	 <p>SOT23 (TO-236AB)</p>	 <p>mbb076</p>
2	S	source		
3	D	drain		

## 3. Ordering information

Table 3. Ordering information

Type number	Package		Version
	Name	Description	
PMV22EN	TO-236AB	plastic surface-mounted package; 3 leads	SOT23

## 4. Limiting values

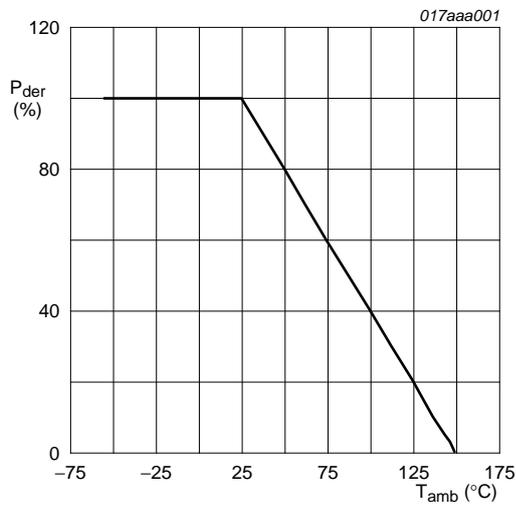
Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit	
$V_{DS}$	drain-source voltage	$T_{amb} = 25\text{ °C}$	-	30	V	
$V_{GS}$	gate-source voltage		-20	20	V	
$I_D$	drain current	$V_{GS} = 10\text{ V}; T_{amb} = 25\text{ °C}$	[1]	-	5.2	A
		$V_{GS} = 10\text{ V}; T_{amb} = 100\text{ °C}$	[1]	-	3.3	A
$I_{DM}$	peak drain current	$T_{amb} = 25\text{ °C};$ single pulse; $t_p \leq 10\text{ }\mu\text{s}$	-	20	A	
$P_{tot}$	total power dissipation	$T_{amb} = 25\text{ °C}$	[2]	-	510	mW
			[1]	-	930	mW
		$T_{sp} = 25\text{ °C}$		-	4170	mW
$T_j$	junction temperature		-	150	°C	
$T_{amb}$	ambient temperature		-55	150	°C	
$T_{stg}$	storage temperature		-65	150	°C	
<b>Source-drain diode</b>						
$I_S$	source current	$T_{amb} = 25\text{ °C}$	[1]	-	930	mA

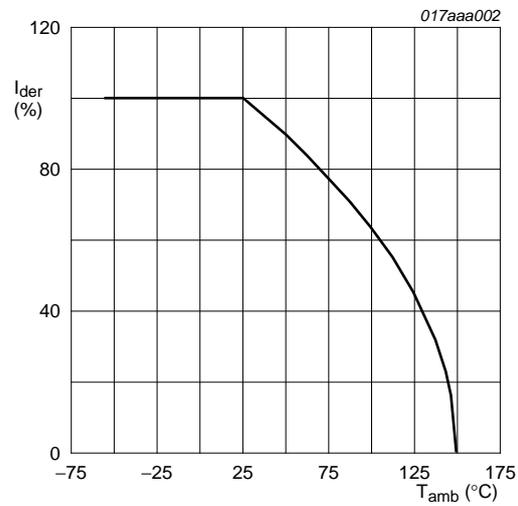
[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm<sup>2</sup>.

[2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.



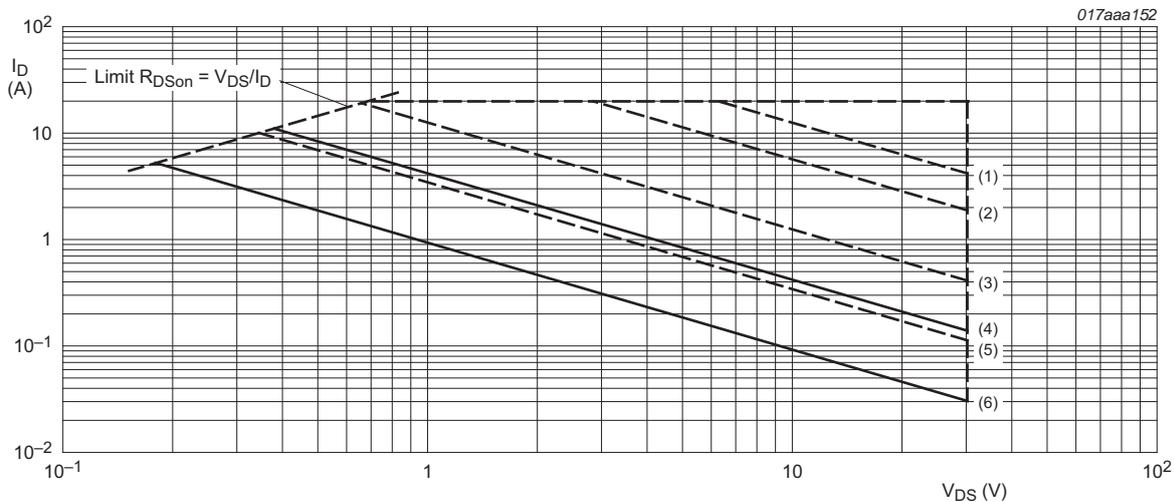
$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}\text{C})}} \times 100\%$$

Fig 1. Normalized total power dissipation as a function of ambient temperature



$$I_{der} = \frac{I_D}{I_{D(25^{\circ}\text{C})}} \times 100\%$$

Fig 2. Normalized continuous drain current as a function of ambient temperature



- $I_{DM}$  = single pulse
- (1)  $t_p = 100 \mu\text{s}$
  - (2)  $t_p = 1 \text{ ms}$
  - (3)  $t_p = 10 \text{ ms}$
  - (4) DC;  $T_{sp} = 25^{\circ}\text{C}$
  - (5)  $t_p = 100 \text{ ms}$
  - (6) DC;  $T_{amb} = 25^{\circ}\text{C}$ ; drain mounting pad  $6 \text{ cm}^2$

Fig 3. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

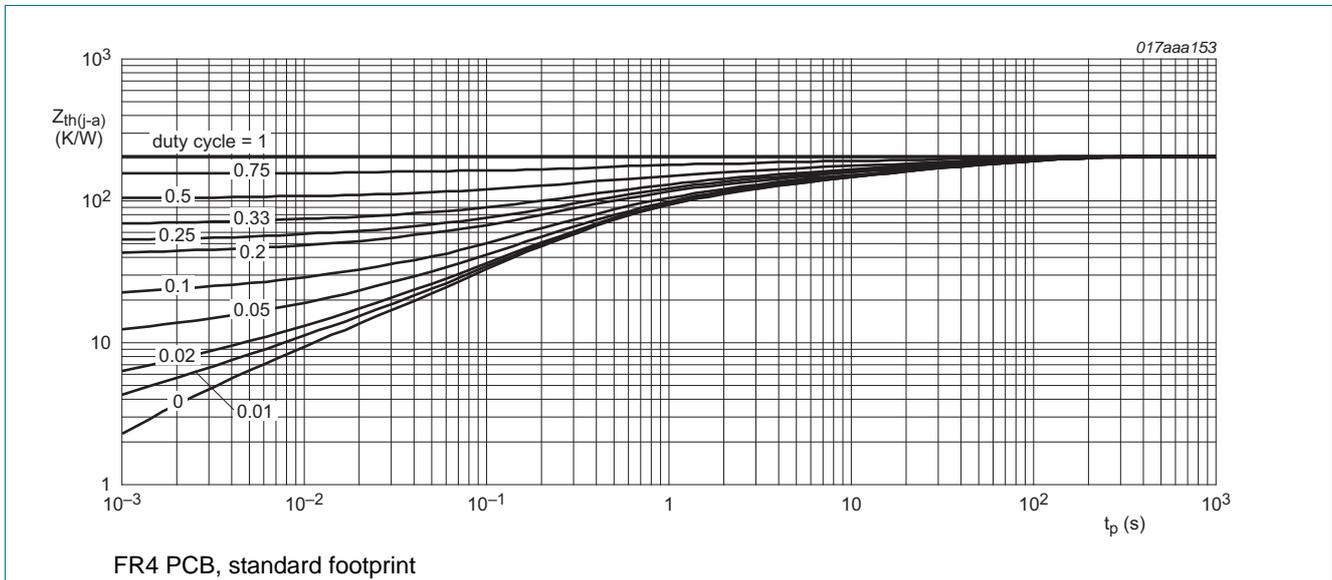
### 5. Thermal characteristics

**Table 5. Thermal characteristics**

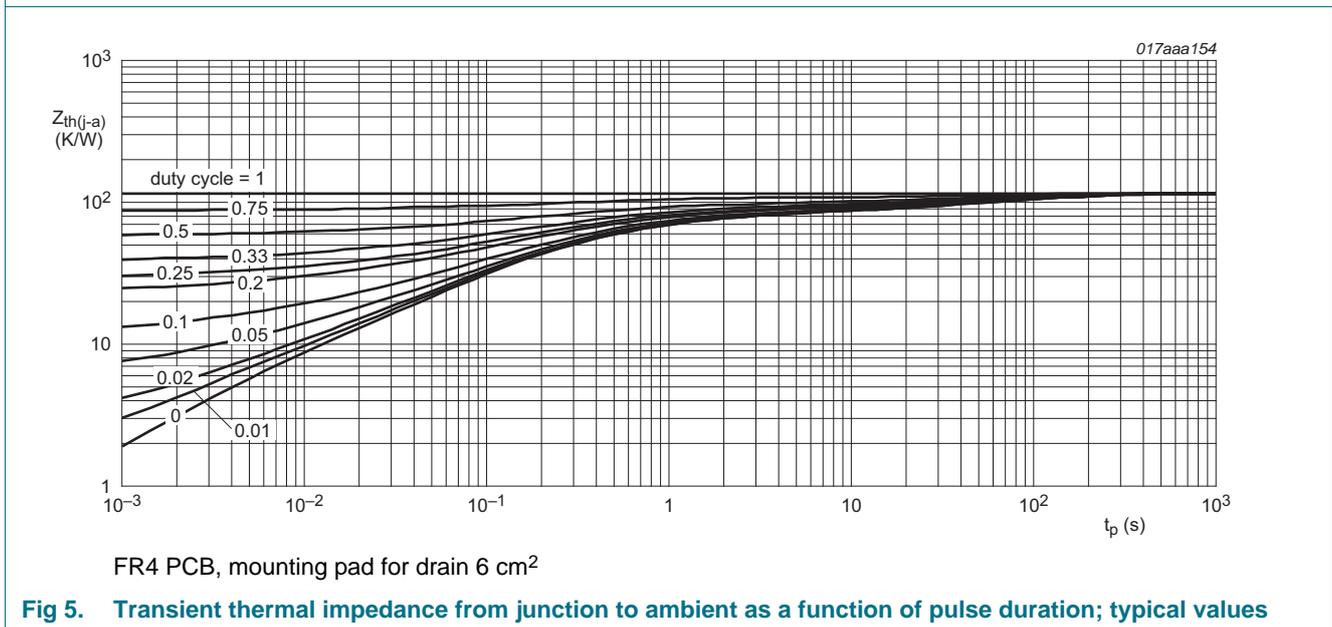
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	[1]	-	207	245	K/W
		[2]	-	116	135	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		-	20	30	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 6 cm<sup>2</sup>.



**Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values**

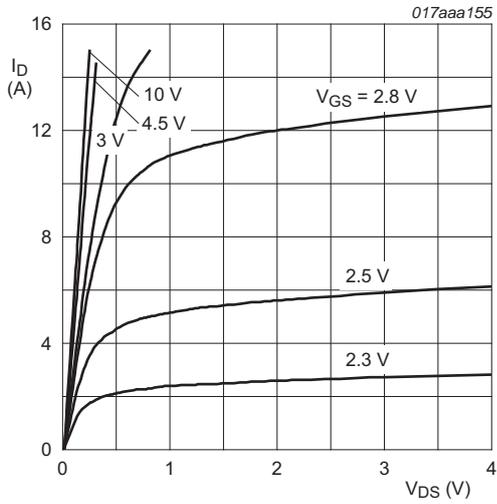


**Fig 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values**

## 6. Characteristics

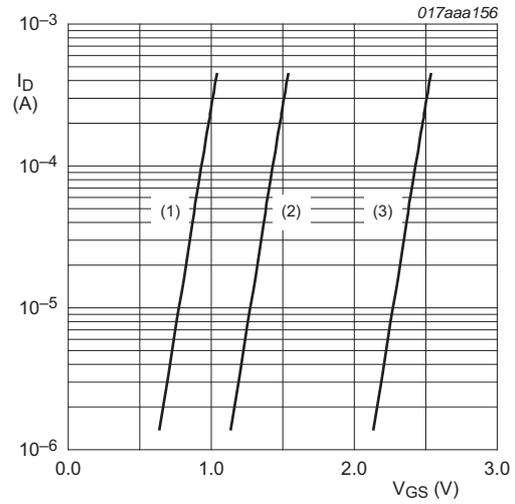
Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250 \mu A$ ; $V_{GS} = 0 V$ ; $T_j = 25 \text{ }^\circ C$	30	-	-	V
$V_{GSth}$	gate-source threshold voltage	$I_D = 250 \mu A$ ; $V_{DS} = V_{GS}$ ; $T_j = 25 \text{ }^\circ C$	1	1.5	2.5	V
$I_{DSS}$	drain leakage current	$V_{DS} = 30 V$ ; $V_{GS} = 0 V$ ; $T_{amb} = 25 \text{ }^\circ C$	-	-	1	$\mu A$
		$V_{DS} = 30 V$ ; $V_{GS} = 0 V$ ; $T_{amb} = 150 \text{ }^\circ C$	-	-	10	$\mu A$
$I_{GSS}$	gate leakage current	$V_{GS} = 20 V$ ; $V_{DS} = 0 V$ ; $T_j = 25 \text{ }^\circ C$	-	-	100	nA
		$V_{GS} = -20 V$ ; $V_{DS} = 0 V$ ; $T_j = 25 \text{ }^\circ C$	-	-	100	nA
$R_{DSon}$	drain-source on-state resistance	$V_{GS} = 10 V$ ; $I_D = 5.2 A$ ; pulsed; $t_p \leq 300 \mu s$ ; $\delta \leq 0.01$ ; $T_j = 25 \text{ }^\circ C$	-	17	22	m $\Omega$
		$V_{GS} = 10 V$ ; $I_D = 5.2 A$ ; pulsed; $t_p \leq 300 \mu s$ ; $\delta \leq 0.01$ ; $T_j = 150 \text{ }^\circ C$	-	27	34	m $\Omega$
		$V_{GS} = 4.5 V$ ; $I_D = 4.5 A$ ; pulsed; $t_p \leq 300 \mu s$ ; $\delta \leq 0.01$ ; $T_j = 25 \text{ }^\circ C$	-	22	29	m $\Omega$
$g_{fs}$	forward transconductance	$V_{DS} = 5 V$ ; $I_D = 3 A$ ; pulsed; $t_p \leq 300 \mu s$ ; $\delta \leq 0.01$ ; $T_j = 25 \text{ }^\circ C$	-	12	-	S
<b>Dynamic characteristics</b>						
$Q_{G(tot)}$	total gate charge	$I_D = 3 A$ ; $V_{DS} = 15 V$ ; $V_{GS} = 10 V$ ; $T_j = 25 \text{ }^\circ C$	-	8.6	13	nC
$Q_{GS}$	gate-source charge		-	1.2	-	nC
$Q_{GD}$	gate-drain charge		-	1.3	-	nC
$C_{iss}$	input capacitance	$V_{GS} = 0 V$ ; $V_{DS} = 15 V$ ; $f = 1 \text{ MHz}$ ; $T_j = 25 \text{ }^\circ C$	-	480	-	pF
$C_{oss}$	output capacitance		-	110	-	pF
$C_{rss}$	reverse transfer capacitance		-	52	-	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 15 V$ ; $V_{GS} = 10 V$ ; $R_{G(ext)} = 6 \Omega$ ; $T_j = 25 \text{ }^\circ C$ ; $I_D = 3 A$	-	4	-	ns
$t_r$	rise time		-	15	-	ns
$t_{d(off)}$	turn-off delay time		-	100	-	ns
$t_f$	fall time		-	40	-	ns
<b>Source-drain diode</b>						
$V_{SD}$	source-drain voltage	$I_S = 0.93 A$ ; $V_{GS} = 0 V$ ; $T_j = 25 \text{ }^\circ C$	-	0.72	1.2	V



$T_j = 25\text{ }^\circ\text{C}$

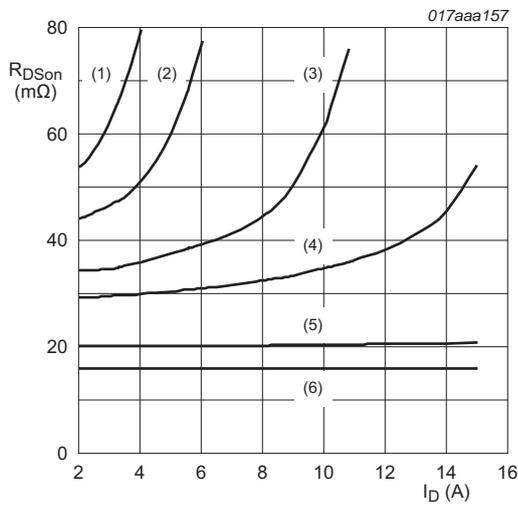
**Fig 6. Output characteristics: drain current as a function of drain-source voltage; typical values**



$T_j = 25\text{ }^\circ\text{C}; V_{DS} = 5\text{ V}$

- (1) minimum values
- (2) typical values
- (3) maximum values

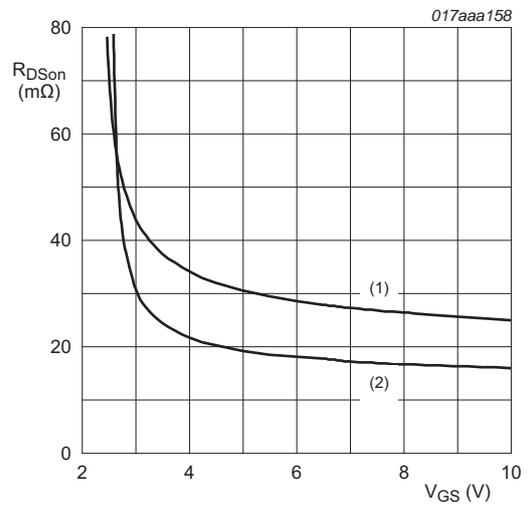
**Fig 7. Sub-threshold drain current as a function of gate-source voltage**



$T_j = 25\text{ }^\circ\text{C}$

- (1)  $V_{GS} = 2.5\text{ V}$
- (2)  $V_{GS} = 2.6\text{ V}$
- (3)  $V_{GS} = 2.8\text{ V}$
- (4)  $V_{GS} = 3.0\text{ V}$
- (5)  $V_{GS} = 4.5\text{ V}$
- (6)  $V_{GS} = 10\text{ V}$

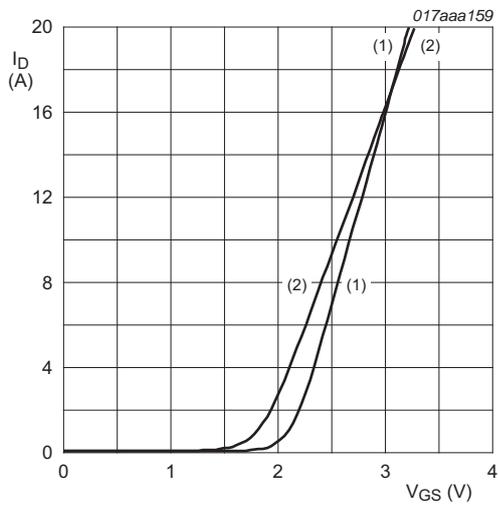
**Fig 8. Drain-source on-state resistance as a function of drain current; typical values**



$I_D = 5.3\text{ A}$

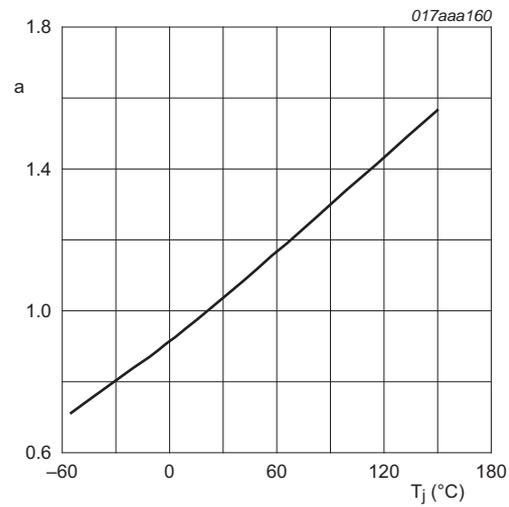
- (1)  $T_j = 150\text{ }^\circ\text{C}$
- (2)  $T_j = 25\text{ }^\circ\text{C}$

**Fig 9. Drain-source on-state resistance as a function of gate-source voltage; typical values**



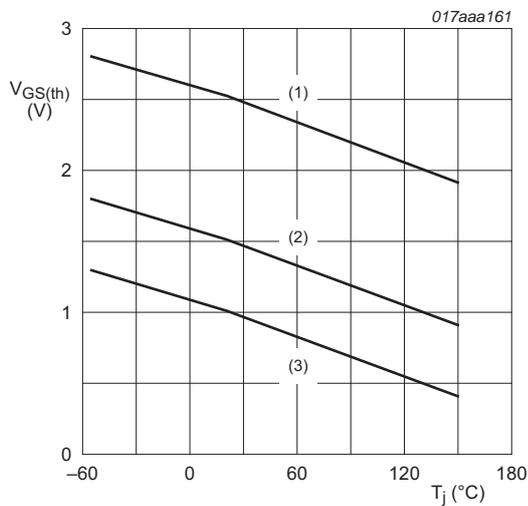
$V_{DS} > I_D \times R_{DS(on)}$   
 (1)  $T_j = 25\text{ °C}$   
 (2)  $T_j = 150\text{ °C}$

Fig 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values



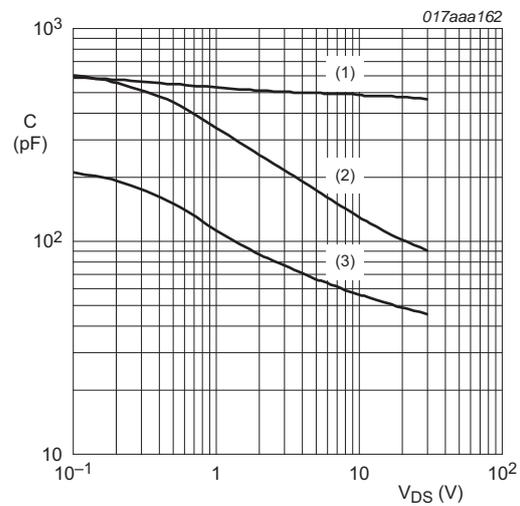
$$a = \frac{R_{DS(on)}}{R_{DS(on)(25^\circ\text{C})}}$$

Fig 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values



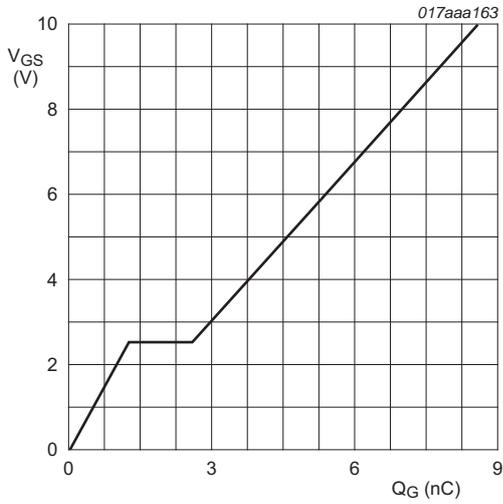
$I_D = 0.25\text{ mA}; V_{DS} = V_{GS}$   
 (1) maximum values  
 (2) typical values  
 (3) minimum values

Fig 12. Gate-source threshold voltage as a function of junction temperature



$f = 1\text{ MHz}; V_{GS} = 0\text{ V}$   
 (1)  $C_{iss}$   
 (2)  $C_{oss}$   
 (3)  $C_{rss}$

Fig 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



$I_D = 3$  A;  $V_{DS} = 15$  V;  $T_{amb} = 25$  °C

Fig 14. Gate-source voltage as a function of gate charge; typical values

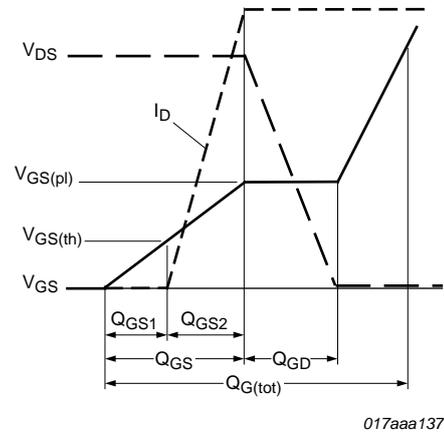
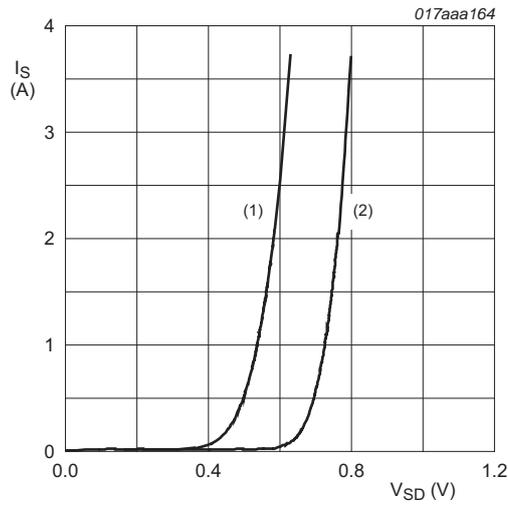


Fig 15. Gate charge waveform definitions



$V_{GS} = 0$  V  
 (1)  $T_j = 150$  °C  
 (2)  $T_j = 25$  °C

Fig 16. Source current as a function of source-drain voltage; typical values

7. Package outline

Plastic surface-mounted package; 3 leads

SOT23

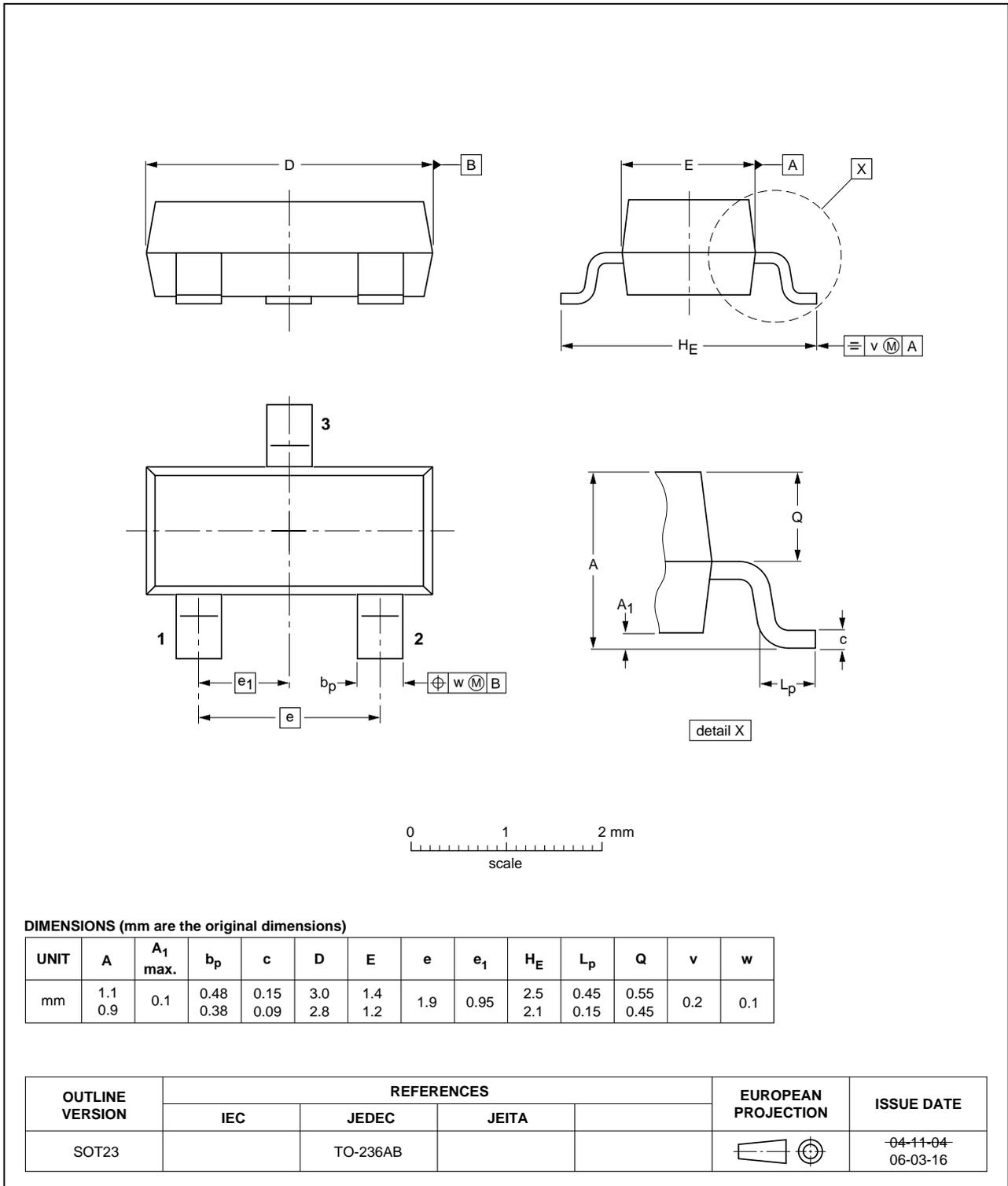


Fig 17. Package outline SOT23 (TO-236AB)

### 8. Soldering

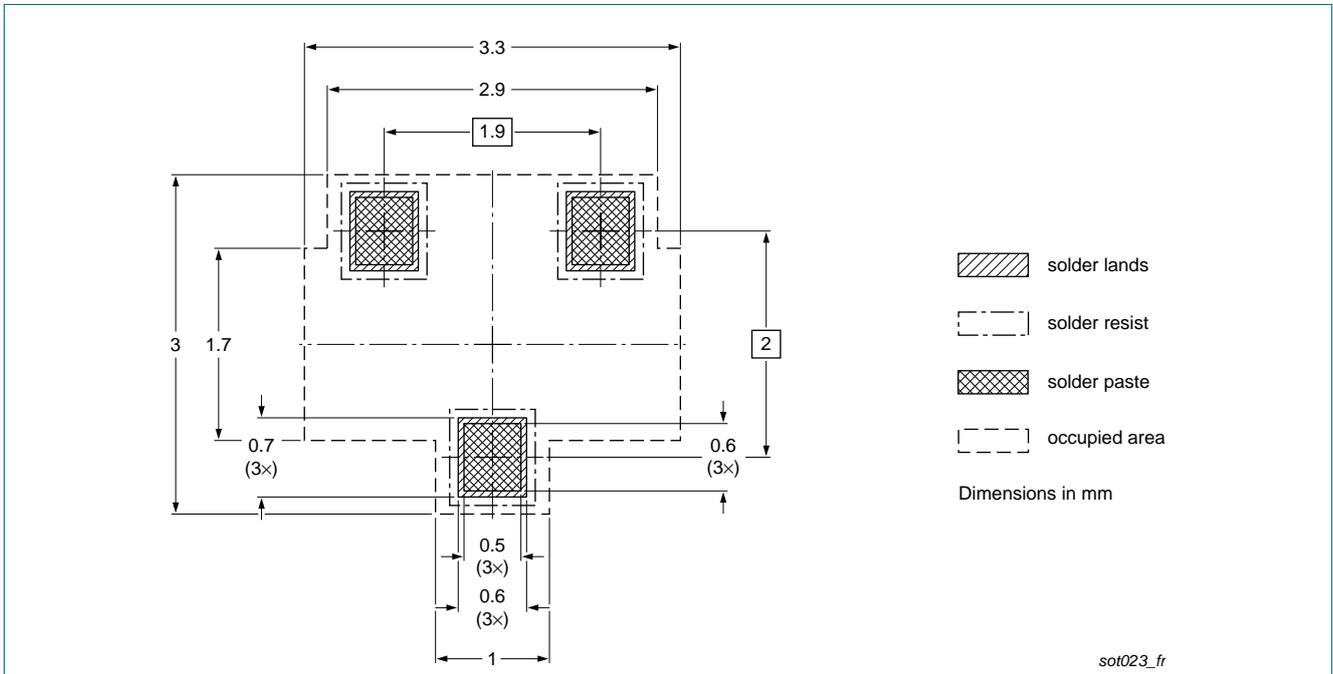


Fig 18. Reflow soldering footprint for SOT23 (TO-236AB)

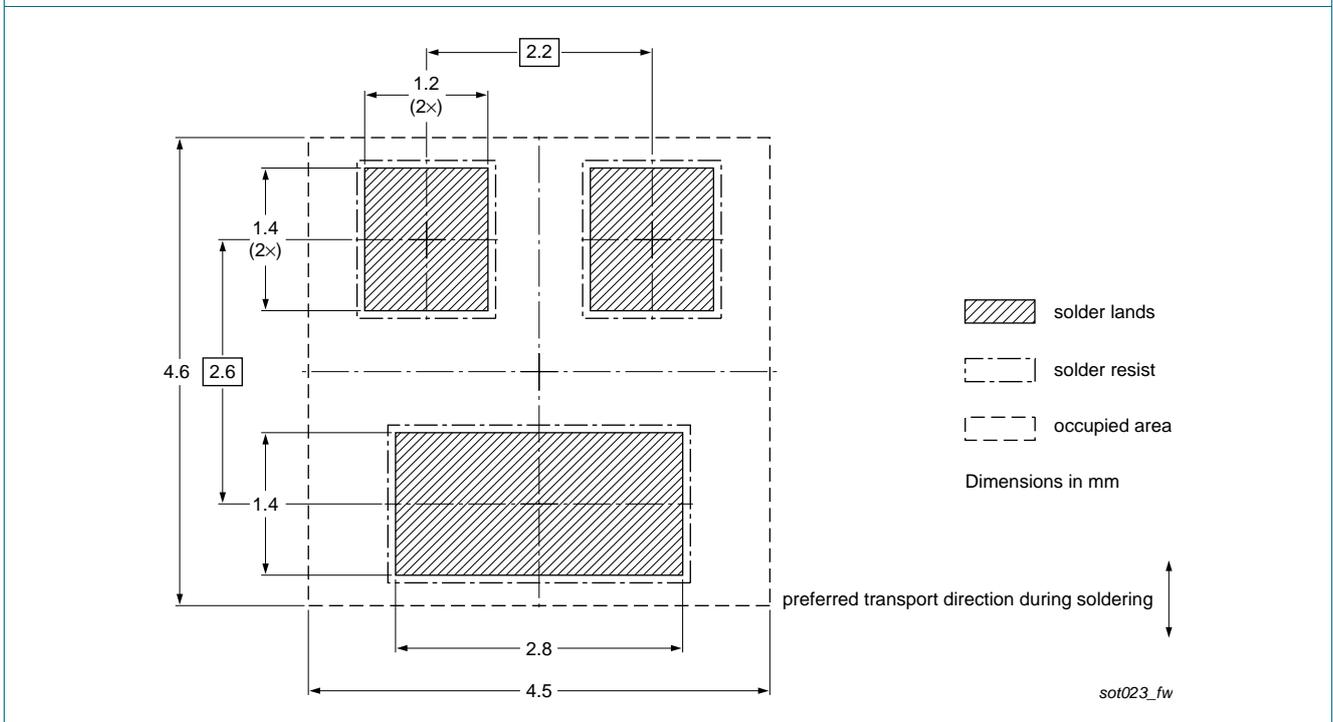


Fig 19. Wave soldering footprint for SOT23 (TO-236AB)

## 9. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PMV22EN v.1	20110330	Product data sheet	-	-

## 10. Legal information

### 10.1 Data sheet status

Document status <sup>[1]</sup> <sup>[2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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